# ANALOG<br/>DEVICESHigh Speed, ESD-Protected, Half-/Full-Duplex,<br/>*i*Coupler Isolated RS-485 Transceiver

# ADM2491E

### FEATURES

Isolated, RS-485/RS-422 transceiver, configurable as half- or full-duplex ±8 kV ESD protection on RS-485 input/output pins 16 Mbps data rate Complies with ANSI TIA/EIA RS-485-A-1998 and ISO 8482: 1987(E) Suitable for 5 V or 3.3 V operation (V<sub>DD1</sub>) High common-mode transient immunity: >25 kV/µs Receiver has open-circuit, fail-safe design 32 nodes on the bus **Thermal shutdown protection** Safety and regulatory approvals pending UL recognition: 5000 V rms isolation voltage for 1 minute, per UL 1577 **VDE** certificate of conformity DIN V VDE V 0884-10 (VDE V 0884-10): 2006-12 Reinforced insulation, VIORM = 848 V peak Operating temperature range: -40°C to +85°C Wide body, 16-lead SOIC package

### APPLICATIONS

Isolated RS-485/RS-422 interfaces Industrial field networks INTERBUS Multipoint data transmission systems

# **GENERAL DESCRIPTION**

The ADM2491E is an isolated data transceiver with  $\pm 8$  kV ESD protection and is suitable for high speed, half- or full-duplex communication on multipoint transmission lines. For halfduplex operation, the transmitter outputs and the receiver inputs share the same transmission line. Transmitter output Pin Y is linked externally to receiver input Pin A, and transmitter output Pin Z to receiver input Pin B.

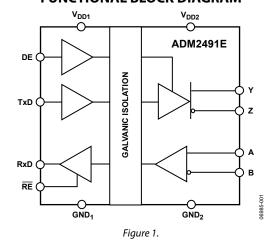
The ADM2491E is designed for balanced transmission lines and complies with ANSI TIA/EIA RS-485-A-1998 and ISO 8482: 1987(E). The device employs Analog Devices, Inc., *i*Coupler\* technology to combine a 3-channel isolator, a threestate differential line driver, and a differential input receiver into a single package. The differential transmitter outputs and receiver inputs feature electrostatic discharge circuitry that provides protection to  $\pm 8$  kV using the human body model (HBM). The logic side of the device can be powered with either a 5 V or a 3.3 V supply, whereas the bus side requires an isolated 5 V supply.

The device has current-limiting and thermal shutdown features to protect against output short circuits and situations where bus contention could cause excessive power dissipation.

The ADM2491E is available in a wide body, 16-lead SOIC package and operates over the  $-40^{\circ}$ C to  $+85^{\circ}$ C temperature range.

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# FUNCTIONAL BLOCK DIAGRAM



 One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106, U.S.A.

 Tel: 781.329.4700
 www.analog.com

 Fax: 781.461.3113
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# **REVISION HISTORY**

10/07—Revision 0: Initial Version

# **SPECIFICATIONS**

All voltages are relative to their respective ground;  $3.0 \text{ V} \le V_{DD1} \le 5.5 \text{ V}$ ,  $4.5 \text{ V} \le V_{DD2} \le 5.5 \text{ V}$ . All minimum/maximum specifications apply over the entire recommended operation range, unless otherwise noted. All typical specifications are at  $T_A = 25^{\circ}C$ ,  $V_{DD1} = V_{DD2} = 5.0 \text{ V}$ , unless otherwise noted.

Table	1.
1 4010	

Parameter	Symbol	Min	Тур	Max	Unit	Test Conditions
SUPPLY CURRENT						
Power Supply Current, Logic Side						
TxD/RxD Data Rate = 2 Mbps	I <sub>DD1</sub>			3.0	mA	Unloaded output
TxD/RxD Data Rate = 16 Mbps	I <sub>DD1</sub>			6	mA	Half-duplex configuration,
						R <sub>TERMINATION</sub> = 120 $\Omega$ , see Figure 5
Power Supply Current, Bus Side						
TxD/RxD Data Rate = 2 Mbps	I <sub>DD2</sub>			4.0	mA	Unloaded output
TxD/RxD Data Rate = 16 Mbps	I <sub>DD2</sub>			50	mA	$V_{DD2} = 5.5$ V, half-duplex configuration, R <sub>TERMINATION</sub> = 120 Ω, see Figure 5
DRIVER						Thermination – 12032, See Figure 5
Differential Outputs						
Differential Output Voltage,	Vod	2.0		5.0	v	$R_L = 100 \Omega$ (RS-422), see Figure 3
Loaded	1.001			010		···· ·································
		1.5		5.0	V	$R_L = 54 \Omega$ (RS-485), see Figure 3
		1.5		5.0	V	$-7 \text{ V} \leq \text{V}_{\text{TEST1}} \leq 12 \text{ V}$ , see Figure 4
$\Delta  V_{OD} $ for Complementary	ΔVod			0.2	V	$R_L = 54 \Omega$ or 100 $\Omega$ , see Figure 3
Output States						
Common-Mode Output Voltage	Voc			3.0	V	$R_L = 54 \Omega$ or 100 $\Omega$ , see Figure 3
Δ V <sub>oc</sub>   for Complementary Output States	Δ Voc			0.2	V	$R_L$ = 54 $\Omega$ or 100 $\Omega$ , see Figure 3
Output Leakage Current (Y, Z)	lo			100	μA	$DE = 0 V, V_{DD2} = 0 V \text{ or } 5 V, V_{IN} = 12 V$
	6	-100			μA	$DE = 0 V, V_{DD2} = 0 V \text{ or } 5 V, V_{IN} = -7 V$
Short-Circuit Output Current	los			250	mA	
Logic Inputs DE, RE, TxD	00					
Input Threshold Low	VILTxD	$0.25 \times V_{DD1}$			V	
Input Threshold High	VIHTRXD			$0.7 \times V_{DD1}$	V	
Input Current	I <sub>TxD</sub>	-10	+0.01	+10	μA	
RECEIVER						
Differential Inputs						
Differential Input Threshold	V <sub>TH</sub>	-0.2		+0.2	V	
Input Voltage Hysteresis	V <sub>HYS</sub>		30		mV	$V_{OC} = 0 V$
Input Current (A, B)	h			+1.0	mA	$V_{OC} = 12 V$
		-0.8			mA	$V_{OC} = -7 V$
Line Input Resistance	R <sub>IN</sub>	12			kΩ	
Logic Outputs						
Output Voltage Low	VOLRXD		0.2	0.4	V	$I_{ORxD} = 1.5 \text{ mA}, V_A - V_B = -0.2 \text{ V}$
Output Voltage High	VOHRxD	V <sub>DD1</sub> - 0.3	V <sub>DD1</sub> - 0.2		V	$I_{ORxD} = -1.5 \text{ mA}, V_A - V_B = 0.2 \text{ V}$
Short-Circuit Current				100	mA	
Three-State Output Leakage	Iozr			±1	μΑ	V <sub>DD1</sub> = 5.5 V, 0 V < V <sub>OUT</sub> < V <sub>DD1</sub>
COMMON-MODE TRANSIENT		25			kV/μs	$V_{CM} = 1$ kV, transient magnitude = 800 V
IMMUNITY <sup>1</sup>						

<sup>1</sup> CM is the maximum common-mode voltage slew rate that can be sustained while maintaining specification-compliant operation. V<sub>CM</sub> is the common-mode potential difference between the logic and bus sides. The transient magnitude is the range over which the common mode is slewed. The common-mode voltage slew rates apply to both rising and falling common-mode voltage edges.

### TIMING SPECIFICATIONS

 $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ 

### Table 2.

Parameter	Symbol	Min	Тур	Max	Unit	Test Conditions
DRIVER						
Maximum Data Rate		16			Mbps	
Propagation Delay	t <sub>PLH</sub> , t <sub>PHL</sub>		45	60	ns	$R_L = 54 \Omega$ , $C_{L1} = C_{L2} = 100 \text{ pF}$ , see Figure 6 and Figure 10
Pulse Width Distortion, $PWD =  t_{PYLH} - t_{PYHL} , PWD =  t_{PZLH} - t_{PZHL} $	$t_{PWD}$ , $t_{PWD}$			7	ns	$R_L = 54 \Omega$ , $C_{L1} = C_{L2} = 100 \text{ pF}$ , see Figure 6 and Figure 10
Single-Ended Output Rise/Fall Times	t <sub>R</sub> , t <sub>F</sub>			20	ns	$R_L = 54 \Omega$ , $C_{L1} = C_{L2} = 100 \text{ pF}$ , see Figure 6 and Figure 10
Enable Time				55	ns	$R_L = 110 \Omega$ , $C_L = 50 pF$ , see Figure 8 and Figure 11
Disable Time				55	ns	$R_L = 110 \Omega$ , $C_L = 50 pF$ , see Figure 8 and Figure 11
RECEIVER						
Propagation Delay	tplh, tphl			60	ns	$C_{L} = 15 \text{ pF}$ , see Figure 7 and Figure 12
Pulse Width Distortion, $PWD =  t_{PLH} - t_{PHL} $	t <sub>PWD</sub>			10	ns	$C_L = 15 \text{ pF}$ , see Figure 7 and Figure 12
Enable Time				13	ns	$R_L = 1 k\Omega$ , $C_L = 15 pF$ , see Figure 9 and Figure 13
Disable Time				13	ns	$R_L = 1 k\Omega$ , $C_L = 15 pF$ , see Figure 9 and Figure 13

# PACKAGE CHARACTERISTICS

### Table 3.

Parameter	Symbol	Min	Тур	Мах	Unit	Test Conditions
Resistance (Input to Output) <sup>1</sup>	R <sub>I-O</sub>		10 <sup>12</sup>		Ω	
Capacitance (Input to Output) <sup>1</sup>	CI-O		3		pF	f = 1 MHz
Input Capacitance <sup>2</sup>	Cı		4		pF	
Input IC Junction-to-Case Thermal Resistance	θ」		33		°C/W	Thermocouple located at center of package underside
Output IC Junction-to-Case Thermal Resistance	θιςο		28		°C/W	

<sup>1</sup> Device considered a 2-terminal device: Pin 1, Pin 2, Pin 3, Pin 4, Pin 5, Pin 6, Pin 7, and Pin 8 are shorted together and Pin 9, Pin 10, Pin 10, Pin 11, Pin 12, Pin 13, Pin 14, Pin 15, and Pin 16 are shorted together.

<sup>2</sup> Input capacitance is from any input data pin to ground.

### **REGULATORY INFORMATION (PENDING)**

### Table 4.

UL1	VDE <sup>2</sup>
To be recognized under 1577 component recognition program <sup>1</sup>	To be certified according to DIN V VDE V 0884-10 (VDE V 0884-10): 2006-12 <sup>2</sup>
5000 V rms isolation voltage	Reinforced insulation, 846 V peak

<sup>1</sup> In accordance with UL 1577, each ADM2491E is proof tested by applying an insulation test voltage ≥ 6000 V rms for 1 second (current leakage detection limit = 10 μA). <sup>2</sup> In accordance with DIN V VDE V 0884-10, each ADM2491E is proof tested by applying an insulation test voltage ≥ 1590 V peak for 1 second (partial discharge detection limit = 5 pC).

# INSULATION AND SAFETY-RELATED SPECIFICATIONS

Table 5.

Parameter	Symbol	Value	Unit	Conditions
Rated Dielectric Insulation Voltage		5000	V rms	1 minute duration
Minimum External Air Gap (Clearance)	L(I01)	7.7	mm min	Measured from input terminals to output terminals, shortest distance through air
Minimum External Tracking (Creepage)	L(I02)	8.1	mm min	Measured from input terminals to output terminals, shortest distance along body
Minimum Internal Gap (Internal Clearance)		0.017	mm min	Insulation distance through insulation
Tracking Resistance (Comparative Tracking Index)	СТІ	>175	V	DIN IEC 112/VDE 0303 Part 1
Isolation Group		Illa		Material Group (DIN VDE 0110, 1/89)

# **VDE 0884 INSULATION CHARACTERISTICS (PENDING)**

This isolator is suitable for basic electrical isolation only within the safety limit data. Maintenance of the safety data must be ensured by means of protective circuits.

An asterisk (\*) on a package denotes VDE 0884 approval for 848 V peak working voltage.

Description	Symbol	Characteristic	Unit
Installation Classification per DIN VDE 0110 for Rated Mains Voltage			
≤300 V rms		l to IV	
≤450 V rms		l to ll	
≤600 V rms		l to ll	
Climatic Classification		40/105/21	
Pollution Degree (DIN VDE 0110, see Table 1)		2	
Maximum Working Insulation Voltage	VIORM	846	V peak
Input-to-Output Test Voltage, Method b1	V <sub>PR</sub>	1590	V peak
$V_{IORM} \times 1.875 = V_{PR}$ , 100% Production Tested, $t_m = 1$ sec, Partial Discharge < 5 pC			
Input-to-Output Test Voltage, Method a	VPR		
After Environmental Tests, Subgroup 1		1357	V peak
$V_{IORM} \times 1.6 = V_{PR}$ , $t_m = 60$ sec, Partial Discharge < 5 pC			
After Input and/or Safety Test, Subgroup 2/Subgroup 3		1018	V peak
$V_{IORM} \times 1.2 = V_{PR}$ , $t_m = 60$ sec, Partial Discharge < 5 pC			
Highest Allowable Overvoltage (Transient Overvoltage, $t_{TR} = 10$ sec)	VTR	6000	V peak
Safety-Limiting Values (Maximum Value Allowed in the Event of a Failure; see Figure 20)			
Case Temperature	Ts	150	°C
Input Current	I <sub>s</sub> , input	265	mA
Output Current	Is, OUTPUT	335	mA
Insulation Resistance at $T_{s}$ , $V_{IO} = 500 V$	Rs	>109	Ω

# **ABSOLUTE MAXIMUM RATINGS**

 $T_A = 25$  °C, unless otherwise noted. Each voltage is relative to its respective ground.

### Table 7.

Parameter	Rating
Storage Temperature	−55°C to +150°C
Ambient Operating Temperature	-40°C to +85°C
V <sub>DD1</sub>	–0.5 V to +7 V
V <sub>DD2</sub>	–0.5 V to +6 V
Logic Input Voltages	-0.5 V to V <sub>DD1</sub> + 0.5 V
Bus Terminal Voltages	-9 V to +14 V
Logic Output Voltages	-0.5 V to V <sub>DD1</sub> + 0.5 V
Average Output Current, per Pin	±35 mA
ESD (Human Body Model) on A, B, Y, and Z pins	±8 kV

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

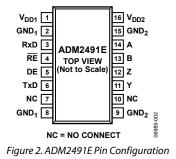
Absolute maximum ratings apply individually only, not in combination.

### **ESD CAUTION**



**ESD** (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

# **PIN CONFIGURATION AND FUNCTIONAL DESCRIPTIONS**



### **Table 8. Pin Function Descriptions**

Pin No.	Mnemonic	Description
1	V <sub>DD1</sub>	Power Supply (Logic Side). Decoupling capacitor to GND1 required; capacitor value should be between 0.01 $\mu F$ and 0.1 $\mu F.$
2	GND1	Ground (Logic Side).
3	RxD	Receiver Output.
4	RE	Receiver Enable Input. Active low logic input. When this pin is low, the receiver is enabled; when high, the receiver is disabled.
5	DE	Driver Enable Input. Active high logic input. When this pin is high, the driver (transmitter) is enabled; when low, the driver is disabled.
6	TxD	Transmit Data.
7	NC	No Connect. This pin must be left floating.
8	GND <sub>1</sub>	Ground (Logic Side).
9	GND <sub>2</sub>	Ground (Bus Side).
10	NC	No Connect. This pin must be left floating.
11	Y	Driver Noninverting Output.
12	Z	Driver Inverting Output.
13	В	Receiver Inverting Input.
14	А	Receiver Noninverting Input.
15	GND <sub>2</sub>	Ground (Bus Side).
16	V <sub>DD2</sub>	Power Supply (Bus Side). Decoupling capacitor to GND_2 required; capacitor value should be between 0.01 $\mu F$ and 0.1 $\mu F$ .

# **TEST CIRCUITS**

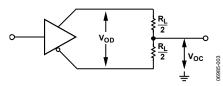


Figure 3. Driver Voltage Measurement

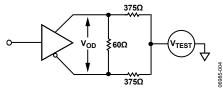


Figure 4. Driver Voltage Measurement

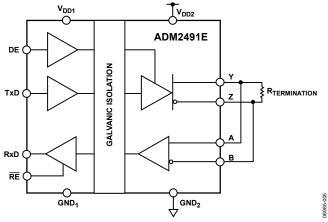


Figure 5. Supply Current Measurement Test Circuit

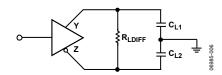


Figure 6. Driver Propagation Delay

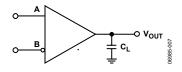


Figure 7. Receiver Propagation Delay

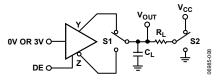


Figure 8. Driver Enable/Disable

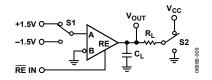
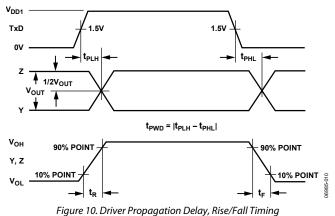


Figure 9. Receiver Enable/Disable

# SWITCHING CHARACTERISTICS



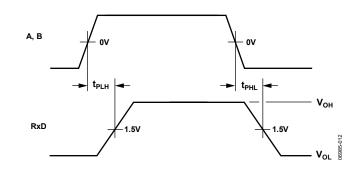
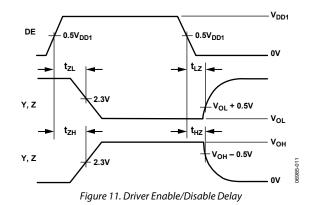
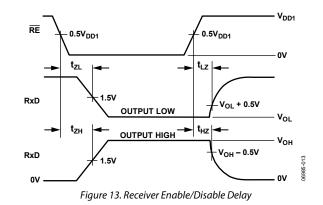


Figure 12. Receiver Propagation Delay





# **TYPICAL PERFORMANCE CHARACTERISTICS**

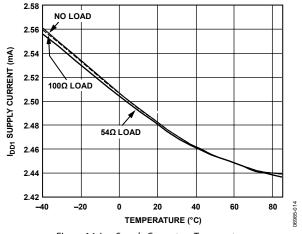
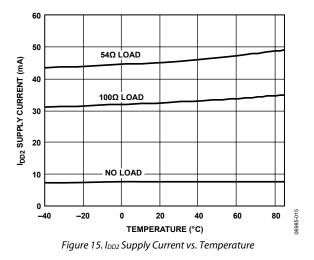
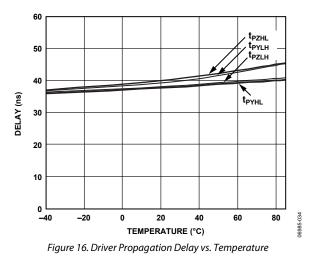


Figure 14. IDD1 Supply Current vs. Temperature





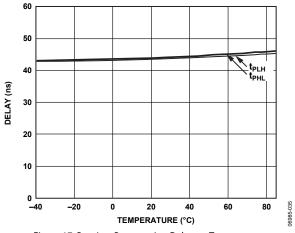


Figure 17. Receiver Propagation Delay vs. Temperature

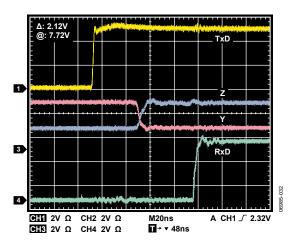


Figure 18. Driver/Receiver Propagation Delay, Low to High  $(R_{LDIFF} = 54 \ \Omega, C_{L1} = C_{L2} = 100 \ pF)$ 

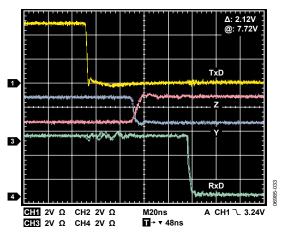
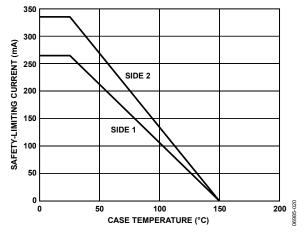
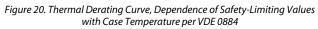


Figure 19. Driver/Receiver Propagation Delay, High to Low  $(R_{LDIFF} = 54 \ \Omega, C_{L1} = C_{L2} = 100 \ pF)$ 





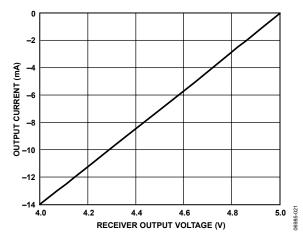


Figure 21. Output Current vs. Receiver Output High Voltage

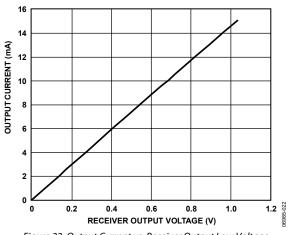
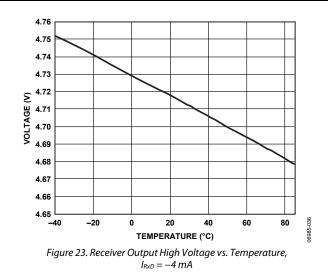
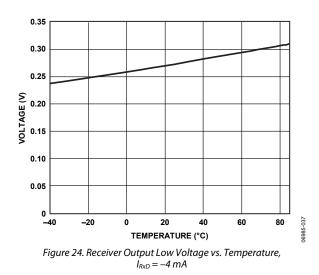


Figure 22. Output Current vs. Receiver Output Low Voltage





# **CIRCUIT DESCRIPTION** ELECTRICAL ISOLATION

In the ADM2491E, electrical isolation is implemented on the logic side of the interface. Therefore, the part has two main sections: a digital isolation section and a transceiver section (see Figure 25). The driver input signal, which is applied to the TxD pin and referenced to logic ground (GND<sub>1</sub>), is coupled across an isolation barrier to appear at the transceiver section referenced to isolated ground (GND<sub>2</sub>). Similarly, the receiver input, which is referenced to isolated ground in the transceiver section, is coupled across the isolation barrier to appear at the RxD pin referenced to logic ground.

### iCoupler Technology

The digital signals are transmitted across the isolation barrier using *i*Coupler technology. This technique uses chip scale transformer windings to couple the digital signals magnetically from one side of the barrier to the other. Digital inputs are encoded into waveforms that are capable of exciting the primary transformer winding. At the secondary winding, the induced waveforms are decoded into the binary value that was originally transmitted.

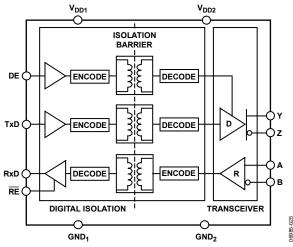


Figure 25. ADM2491E Digital Isolation and Transceiver Sections

### **TRUTH TABLES**

The truth tables in this section use the abbreviations shown in Table 9.

**Table 9. Truth Table Abbreviations** 

Letter	Description
Н	High level
L	Low level
I	Indeterminate
Х	Irrelevant
Z	High impedance (off)
NC	Disconnected

### Table 10. Transmitting

Supply Status			Inputs	0	Outputs	
V <sub>DD1</sub>	V <sub>DD2</sub>	DE	TxD	Y	Z	
On	On	Н	Н	Н	L	
On	On	Н	L	L	н	
On	On	L	Х	Z	Z	
On	Off	Х	Х	Z	Z	
Off	On	L	L	Z	Z	
Off	Off	Х	Х	Z	Z	

Supply Status		Inputs		Output
V <sub>DD1</sub>	V <sub>DD2</sub>	A – B (V)	RE	RxD
On	On	>0.2	L or NC	Н
On	On	<-0.2	L or NC	L
On	On	-0.2 < A - B < +0.2	L or NC	1
On	On	Inputs open	L or NC	н
On	On	Х	Н	Z
On	Off	Х	L or NC	н
Off	Off	Х	L or NC	L

### THERMAL SHUTDOWN

The ADM2491E contains thermal shutdown circuitry that protects the part from excessive power dissipation during fault conditions. Shorting the driver outputs to a low impedance source can result in high driver currents. The thermal sensing circuitry detects the increase in die temperature under this condition and disables the driver outputs. This circuitry is designed to disable the driver outputs when a die temperature of 150°C is reached. As the device cools, the drivers are re-enabled at a temperature of 140°C.

### FAIL-SAFE RECEIVER INPUTS

The receiver inputs include a fail-safe feature that guarantees a logic high on the RxD pin when the A and B inputs are floating or open circuited.

### **MAGNETIC FIELD IMMUNITY**

Because *i*Coupler devices use a coreless technology, no magnetic components are present and the problem of magnetic saturation of the core material does not exist. Therefore, *i*Coupler devices have essentially infinite dc field immunity. The following analysis defines the conditions under which this may occur. The 3 V operating condition of the ADM2491E is examined because it represents the most susceptible mode of operation.

The limitation on the ac magnetic field immunity of the *i*Coupler is set by the condition that induced an error voltage in the receiving coil (the bottom coil in this case) that was large to either falsely set or reset the decoder. The voltage induced across the bottom coil is given by

$$V = -\left(\frac{-d\beta}{dt}\right) \sum \pi r_n^2 ; n = 1, 2, \dots, N$$

where (if the pulses at the transformer output are greater than 1.0 V in amplitude):

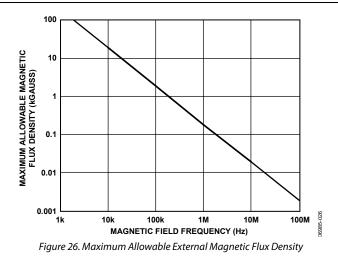
 $\beta$  is the magnetic flux density (gauss).

*N* is the number of turns in receiving coil.

 $r_n$  is the radius of n<sup>th</sup> turn in receiving coil (cm).

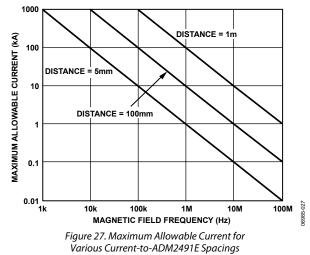
The decoder has a sensing threshold of about 0.5 V; therefore, there is a 0.5 V margin in which induced voltages can be tolerated.

Given the geometry of the receiving coil and an imposed requirement that the induced voltage is, at most, 50% of the 0.5 V margin at the decoder, a maximum allowable magnetic field is calculated, as shown in Figure 26.



For example, at a magnetic field frequency of 1 MHz, the maximum allowable magnetic field of 0.2 kgauss induces a voltage of 0.25 V at the receiving coil. This is about 50% of the sensing threshold and does not cause a faulty output transition. Similarly, if such an event occurs during a transmitted pulse and is the worst-case polarity, it reduces the received pulse from >1.0 V to 0.75 V—still well above the 0.5 V sensing threshold of the decoder.

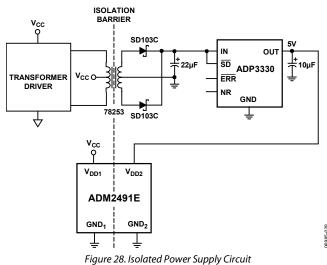
Figure 27 shows the magnetic flux density values in terms of more familiar quantities, such as maximum allowable current flow, at given distances away from the ADM2491E transformers.



With combinations of strong magnetic field and high frequency, any loops formed by printed circuit board traces could induce error voltages large enough to trigger the thresholds of succeeding circuitry. Care should be taken in the layout of such traces to avoid this possibility.

# APPLICATIONS INFORMATION ISOLATED POWER SUPPLY CIRCUIT

The ADM2491E requires isolated power capable of 5 V at up to approximately 75 mA (this current is dependant on the data rate and termination resistors used) to be supplied between the  $V_{DD2}$  and the GND<sub>2</sub> pins. A transformer driver circuit with a center-tapped transformer and LDO can be used to generate the isolated 5 V supply, as shown in Figure 28. The center-tapped transformer provides electrical isolation of the 5 V power supply. The primary winding of the transformer is excited with a pair of square waveforms that are 180° out of phase with each other. A pair of Schottky diodes and a smoothing capacitor are used to create a rectified signal from the secondary winding. The ADP3330 linear voltage regulator provides a regulated power supply to the bus-side circuitry ( $V_{DD2}$ ) of the ADM2491E.



# **PCB LAYOUT**

The ADM2491E isolated RS-485 transceiver requires no external interface circuitry for the logic interfaces. Power supply bypassing is required at the input and output supply pins (see Figure 29). Bypass capacitors are conveniently connected between Pin 1 and Pin 2 for  $V_{DD1}$  and between Pin 15 and Pin 16 for  $V_{DD2}$ . The capacitor value should be between 0.01  $\mu$ F and 0.1  $\mu$ F. The total lead length between both ends of the capacitor and the input power supply pin should not exceed 20 mm. Bypassing between Pin 1 and Pin 8 and between Pin 9 and Pin 16 should also be considered unless the ground pair on each package side is connected close to the package.

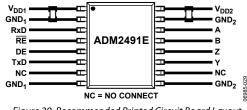


Figure 29. Recommended Printed Circuit Board Layout

In applications involving high common-mode transients, care should be taken to ensure that board coupling across the isolation barrier is minimized. Furthermore, the board layout should be designed such that any coupling that does occur equally affects all pins on a given component side. Failure to ensure this could cause voltage differentials between pins exceeding the absolute maximum ratings of the device, thereby leading to latch-up or permanent damage.

### **TYPICAL APPLICATIONS**

Figure 30 and Figure 31 show typical applications of the ADM2491E in half-duplex and full-duplex RS-485 network configurations. Up to 32 transceivers can be connected to the RS-485 bus. To minimize reflections, the line must be terminated at the receiving end in its characteristic impedance,

and stub lengths off the main line must be kept as short as possible. For half-duplex operation, this means that both ends of the line must be terminated, because either end can be the receiving end.

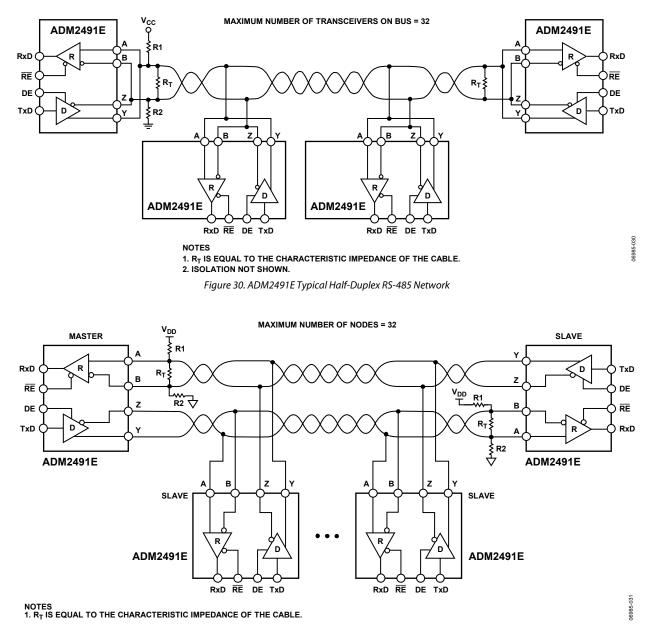
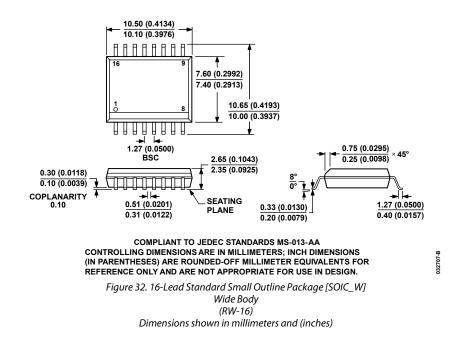


Figure 31. ADM2491E Typical Full -Duplex RS-485 Network

# **OUTLINE DIMENSIONS**



### **ORDERING GUIDE**

Model	Temperature Range	Package Description	Package Option
ADM2491EBRWZ <sup>1</sup>	-40°C to +85°C	16-Lead Standard Small Outline Package, Wide Body [SOIC_W]	RW-16
ADM2491EBRWZ-REEL71	-40°C to +85°C	16-Lead Standard Small Outline Package, Wide Body [SOIC_W]	RW-16

 $^{1}$  Z = RoHS Compliant Part.

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